



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D * : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-06-14
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Giuseppe Vitali Palma	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STD10P10F6	6MDP*6P02B62	A	3068	2017-06-14
Amount	UoM	Unit type	ST ECOPACK Grade	
330.00	mg	Each	ECOPACK2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	6.5-6.1-2.3	3	GULL WING	
Comment	TO 252 DPAK			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

Query : California Prop65 list, dated 27th January 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.01	Die back side metal - Leadframe metal	33
Lead	1.60	Soft solder	4836

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	6MDP*6P02862					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	1.205	mg	supplier	die	Silicon (Si)	7440-21-3		1.168	mg	969295	3539
				supplier	metallization	Aluminium (Al)	7429-90-5		0.014	mg	11618	42
				supplier	Passivation	Silicon Oxide	7631-86-9		0.007	mg	5808	21
				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.001	mg	830	3
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.011	mg	9129	33
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.004	mg	3320	12
Leadframe	Copper & its alloys	164.944	mg	supplier	alloy	Copper (Cu)	7440-50-8		164.152	mg	995198	497430
				supplier	alloy	CopperPhosphorous (CuP)	12517-41-8		0.330	mg	2001	1000
				supplier	alloy	Cobalt (Co)	7440-48-4		0.462	mg	2801	1400
Soft solder	Solder	1.671	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high met	1.596	mg	955117	4836
				supplier	solder	Silver (Ag)	7440-22-4		0.042	mg	25134	127
				supplier	solder	Tin (Sn)	7440-31-5		0.033	mg	19749	100
Bonding wires	Other inorganic materials	0.836	mg	supplier	wire	Copper (Cu)	7440-50-8		0.098	mg	117085	297
				supplier	wire	Aluminium (Al)	7429-90-5		0.738	mg	882915	2239
				supplier	mold compound	Silica, vitreous	60676-86-0		140.261	mg	874996	425033
Encapsulation	Other Organic Materials	160.299	mg	supplier	mold compound	Tetramethyl-biphenyl-diyl-bis oxymethylene-bis	EC 413-900-7		6.412	mg	40000	19430
				supplier	mold compound	Epoxy Resin	25068-38-6		4.809	mg	30000	14573
				supplier	mold compound	phenol resin	29690-82-2		8.015	mg	50000	24288
				supplier	mold compound	Carbon black	1333-86-4		0.802	mg	5004	2430
Connections coating	Solder	1.045	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.045	mg	1000000	3167